

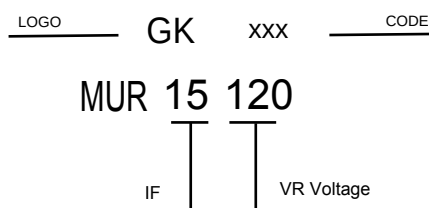
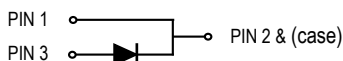


FEATURES

- * Low forward voltage drop
- * High current capability
- * High reliability
- * High surge current capability
- * Epitaxial construction

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Lead: Lead solderable per MIL-STD-202, method 208 guaranteed
- * Polarity: As Marked
- * Mounting position: Any
- * Weight: 1.5 grams



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MUR15120	UNITS
Maximum Recurrent Peak Reverse Voltage	1200	V
Maximum RMS Voltage	1200	V
Maximum DC Blocking Voltage	1200	V
Maximum Average Forward Rectified Current	15.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	180	A
Maximum Instantaneous Forward Voltage at 15.0A	2.5	V
Type at 15.0A	2.1	
Type at 10.0A	1.98	
Type at 5.0 A	1.75	
Maximum DC Reverse Current Ta=25°C	5	μA
at Rated DC Blocking Voltage Ta=100°C	100	μA
Maximum Reverse Recovery Time (Note 1)	60	nS
Typical Junction Capacitance (Note 2)	80	pF
Typical Thermal Resistance RθJ-C (Note 3)	1.8	°C/W
Typical Thermal Resistance RθJ-A (Note 4)	50	°C/W
Reverse recovery charge Q _{rr}	150	nC
Operating and Storage Temperature Range T _J , T _{stg}	-65 — +175	°C

NOTES:

1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Between junction and case
4. Between junction and Air

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

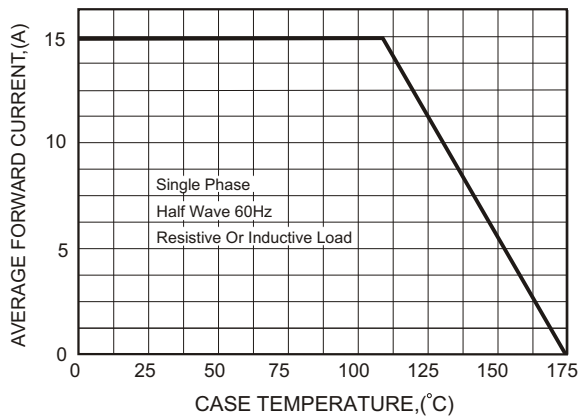


FIG.2-TYPICAL FORWARD CHARACTERISTICS

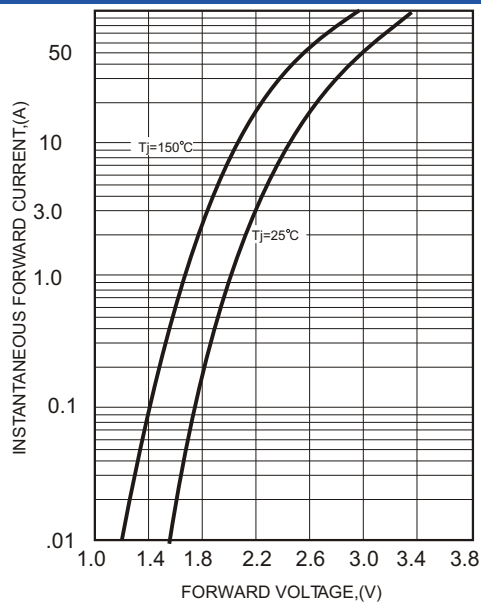


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

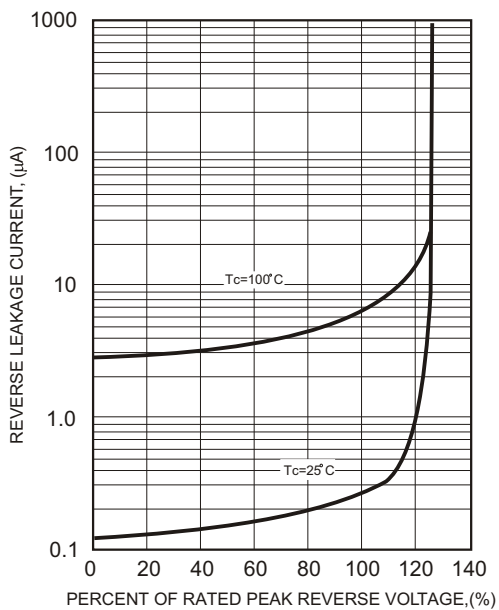
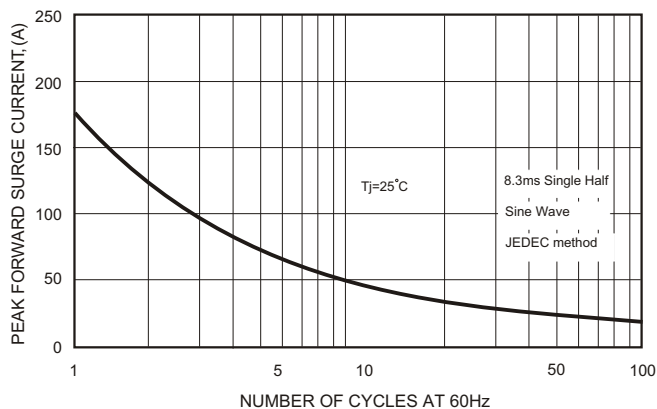
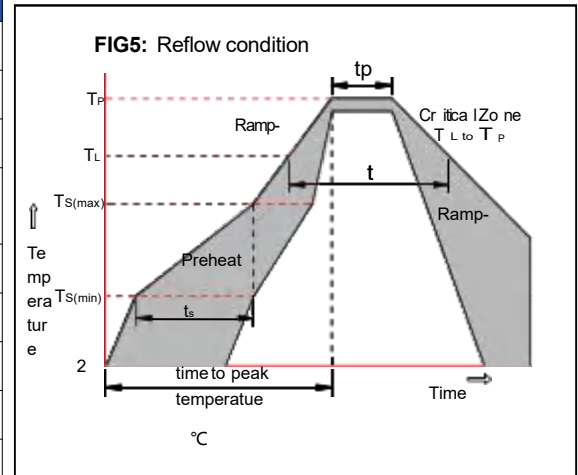


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

